

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 07-045926

(43)Date of publication of application : 14.02.1995

(51)Int.Cl.

H05K 1/18

H05K 1/02

(21)Application number : 05-185124 (71)Applicant : TOYOTA AUTOM LOOM
WORKS LTD

(22)Date of filing : 27.07.1993 (72)Inventor : YOSHIDA TAKASHI

(54) PART MOUNTING BOARD AND MOUNTING METHOD

(57)Abstract:

PURPOSE: To make it possible to secure positively stabilized standoff without increasing the number of steps associated with soldering by satisfying the general-purpose applications of solder paste.

CONSTITUTION: The surface of a stand 10b of a part mounting board 10 is made to protrude from the surface of a conductor part 10a. Under the state, wherein a circuit component 20 is mounted on the surface of the stand 10b, solder paste 30 is provided between the surface of the conductor part 10a and an electrode 20a of the component 20. The holder paste 30 passes reflow process. At this time, the component 20 is supported with the upper surface of the stand 10b. Therefore, the component 20 is mounted on the part mounting substrate 10 under the state, wherein stable standoff ΔH is positively secured.

LEGAL STATUS

[Date of request for examination] 01.02.2000

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

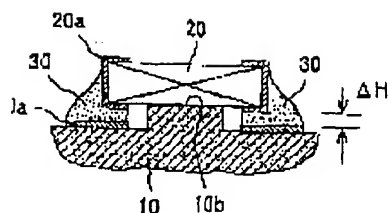
[Date of final disposal for application]
[Patent number]
[Date of registration]
[Number of appeal against examiner's
decision of rejection]
[Date of requesting appeal against
examiner's decision of rejection]
[Date of extinction of right]

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